

MOSFET - Power, N-Channel, SUPERFET® III, **FAST**

650 V, 67 mΩ, 40 A

NTH4LN067N65S3H

Description

SUPERFET III MOSFET is onsemi's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provides superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET FAST series is very suitable for the various power systems for miniaturization and higher efficiency.

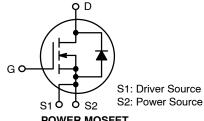
Features

- $700 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ. $R_{DS(on)} = 55 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q_g = 80 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)}= 691 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Telecom / Server Power Supplies
- Industrial Power Supplies
- UPS / Solar

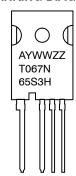
V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	67 m Ω @ 10 V	40 A



POWER MOSFET



MARKING DIAGRAM



YWW 77 T067N65S3H = Assembly Site Code = Data Code (Year & Week)

= Assembly Lot Code = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$, Unless otherwise noted)

Symbol	Parameter	Value	Unit	
V _{DSS}	Drain to Source Voltage	650	V	
V_{GSS}	Gate to Source Voltage	- DC	±30	V
		– AC (f > 1 Hz)	±30	
I _D	Drain Current	– Continuous (T _C = 25°C)	40	Α
		- Continuous (T _C = 100°C)	25	
I _{DM}	Drain Current	- Pulsed (Note 1)	112	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	422	mJ	
I _{AS}	Avalanche Current (Note 2)	6.5	Α	
E _{AR}	Repetitive Avalanche Energy (Note 1)	2.66	mJ	
dv/dt	MOSFET dv/dt	100	V/ns	
	Peak Diode Recovery dv/dt (Note 3)	20		
P_{D}	Power Dissipation	(T _C = 25°C)	266	W
		- Derate Above 25°C	2.13	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C	
TL	Maximum Lead Temperature for Soldering, 1/8"	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
 2. $I_{AS}=6.5$ A, $R_{G}=25$ Ω , starting $T_{J}=25^{\circ}C$.
 3. $I_{SD}\leq 20$ A, di/dt ≤ 200 A/ μ s, $V_{DD}\leq 400$ V, starting $T_{J}=25^{\circ}C$.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.47	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTH4LN067N65S3H	T067N65S3H	TO-247 L4 Narrow Lead	Tube	N/A	N/A	30 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
OFF CHARACTI	ERISTICS				•	•
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V, I}_{D} = 1 \text{ mA, T}_{J} = 25^{\circ}\text{C}$	650	-	_	V
		V _{GS} = 0 V, I _D = 1 mA, T _J = 150°C	700	-	-	V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C	-	0.63	_	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	-	-	2	μΑ
		V _{DS} = 520 V, T _C = 125°C	-	1.6	-	
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V	-	_	±100	nA
ON CHARACTE	RISTICS					•
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 3.9 \text{ mA}$	2.4	-	4.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 20 A	-	55	67	mΩ
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 20 A	-	28	-	S
DYNAMIC CHAP	RACTERISTICS			•		
C _{iss}	Input Capacitance		-	3750	_	pF
C _{oss}	Output Capacitance	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 250 \text{ kHz}$	-	60	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	691	-	pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	107	-	pF
Q _{g(tot)}	Total Gate Charge at 10 V		-	80	-	nC
Q _{gs}	Gate to Source Gate Charge	V _{DS} = 400 V, I _D = 20 A, V _{GS} = 10 V (Note 4)	-	21	-	nC
Q _{gd}	Gate to Drain "Miller" Charge	(18.8.1)	-	20	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.6	-	Ω
SWITCHING CH	ARACTERISTICS					•
t _{d(on)}	Turn-On Delay Time		-	28	_	ns
t _r	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, I_D = 20 \text{ A}, V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$	-	7.2	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, H _g = 4.7 Ω (Note 4)	-	81	-	ns
t _f	Turn-Off Fall Time		-	2.6	_	ns
SOURCE-DRAIN	N DIODE CHARACTERISTICS					•
I _S	Maximum Continuous Source to Drain Diode Forward Current			-	40	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current		-	-	112	Α
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 20 A	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 20 A,	-	411	_	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 \text{ A/}\mu\text{s}$	_	7.8	-	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

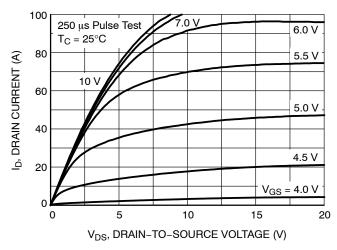


Figure 1. On-Region Characteristics

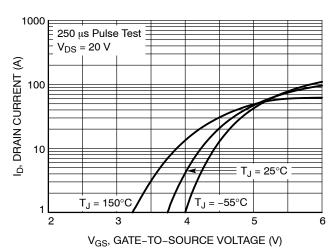


Figure 2. Transfer Characteristics

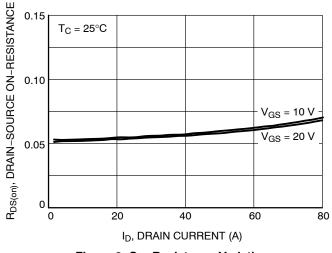


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

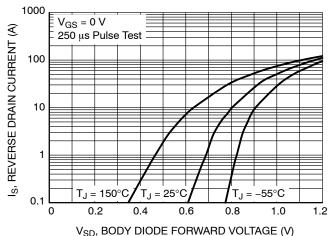


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

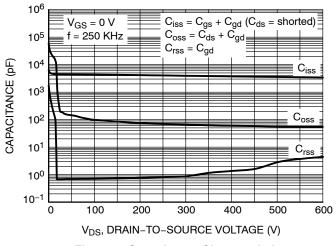


Figure 5. Capacitance Characteristics

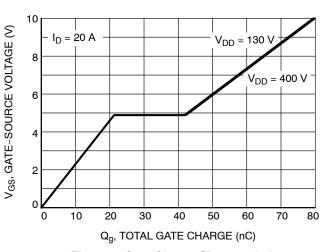


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

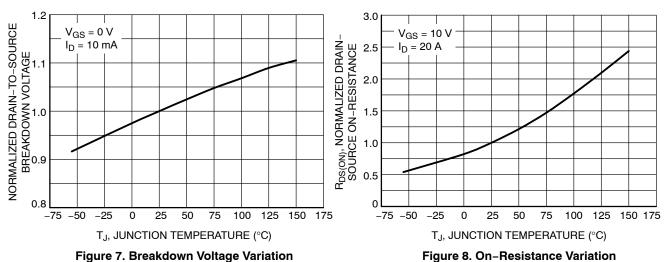


Figure 7. Breakdown Voltage Variation vs. Temperature

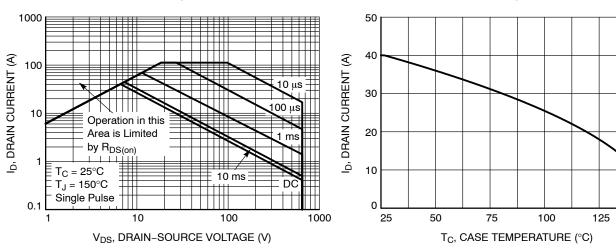


Figure 9. Maximum Safe Operating Area

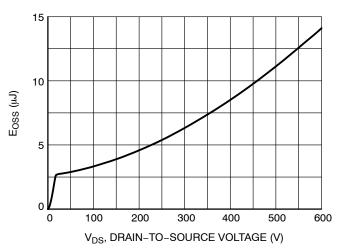


Figure 11. E_{OSS} vs. Drain to Source Voltage

Figure 10. Maximum Drain Current vs. Case Temperature

150

vs. Temperature

TYPICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

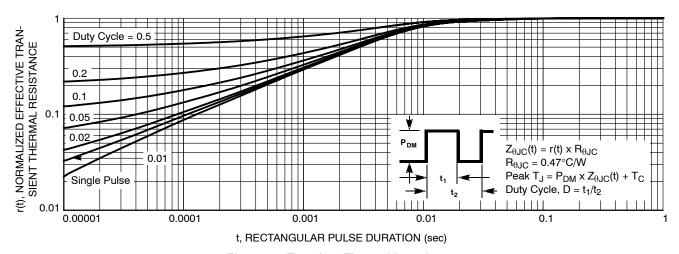


Figure 12. Transient Thermal Impedance

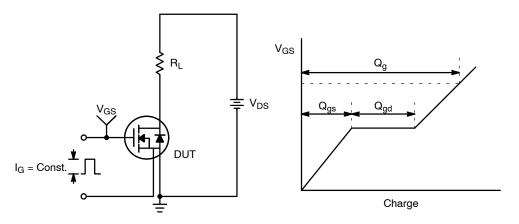


Figure 13. Gate Charge Test Circuit & Waveform

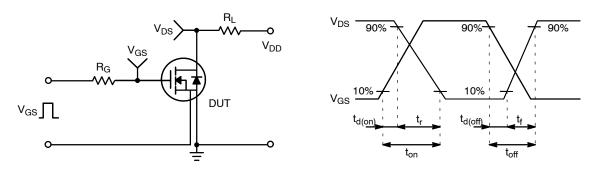


Figure 14. Resistive Switching Test Circuit & Waveforms

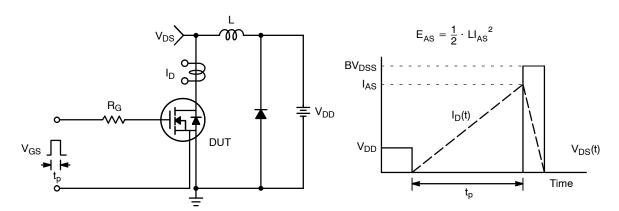


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

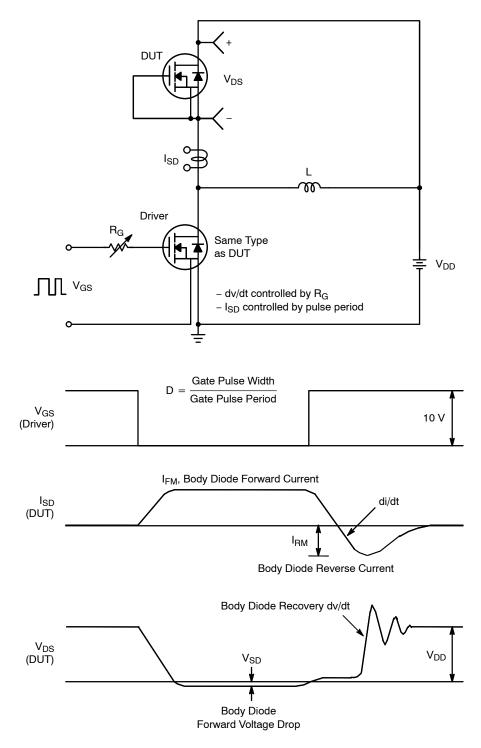
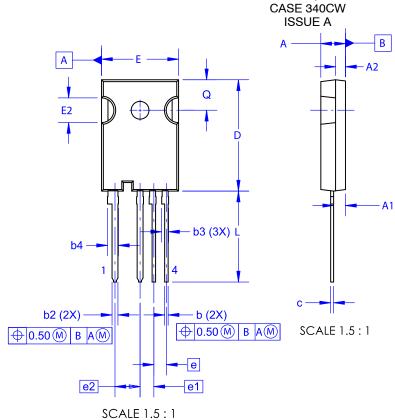


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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PACKAGE DIMENSIONS

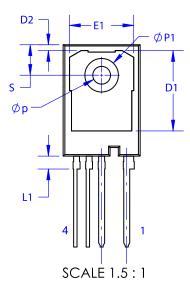
TO-247 4-LEAD, THIN LEADS



NOTES:

- A. NO INDUSTRY STANDARD APPLIES
- TO THIS PACKAGE.

 B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR **EXTRUSIONS**
- C. ALL DIMENSIONS ARE IN MILLIMETERS.



	MILLIMETERS				
DIM	MIN	NOM	MAX		
A	4.80	5.00	5.20		
A1	2.10	2.40	2.70		
	1.80				
A2		2.00	2.20		
b	0.57	0.70	0.83		
b2	1.07	1.20	1.33		
b3	1.20	1.40	1.60		
b4	2.02	2.22	2.42		
С	0.50	0.60	0.70		
D	22.34	22.54	22.74		
D1	16.00	16.30	16.50		
D2	0.97	1.17	1.37		
е		2.54			
e1		2.79			
e2		5.08			
Е	15.40	15.60	15.80		
E1	12.80	13.00	13.20		
E2	4.80	5.00	5.20		
L	18.12	18.42	18.72		
L1	2.42	2.62	2.82		
Øр	3.40	3.60	3.80		
ØP1	6.60	6.80	7.00		
Q	5.97	6.17	6.37		
S	5.97	6.17	6.37		

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